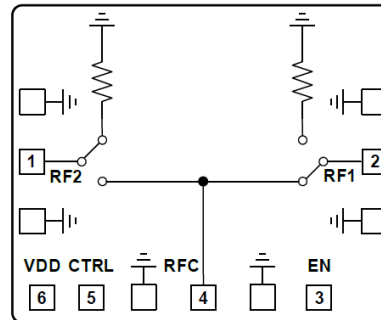


Features

- Positive voltage control
- Isolation: 58dB@ 6GHz
- Insertion Loss: 0.9dB@ 6GHz
- SPDT Matching design
- Power supply: +5V@1.5mA
- Die Size: 1.14x0.97x 0.1 mm

Typical Applications

- TTL compatible driver included
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

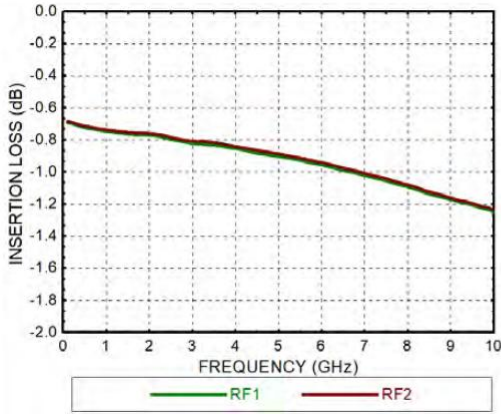
Functional Block Diagram

Electrical Specifications

TA = +25°C, CTRL=0/+3.3V, VDD= +5V

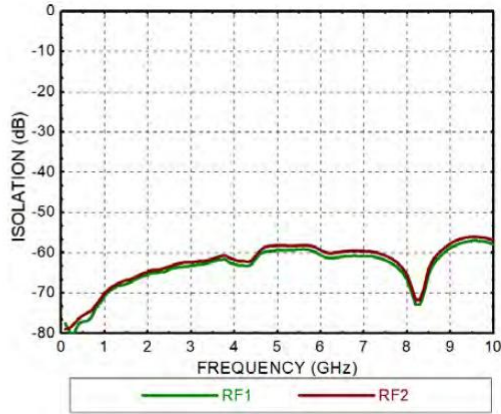
Parameters	Min.	Typ.	Max.	Units
Frequency		0.1-8		GHz
Insertion Loss		0.9		dB
Isolation		60		dB
Return Loss (ON State)		20		dB
Return Loss (OFF State)		20		dB
Input 1dB Compression@1-8GHz		25		dBm
Switching Speed		25		ns



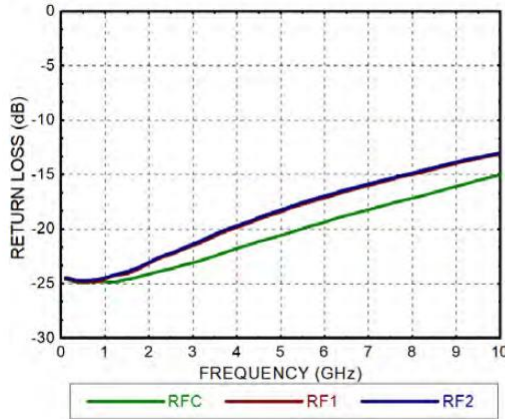
Insertion Loss



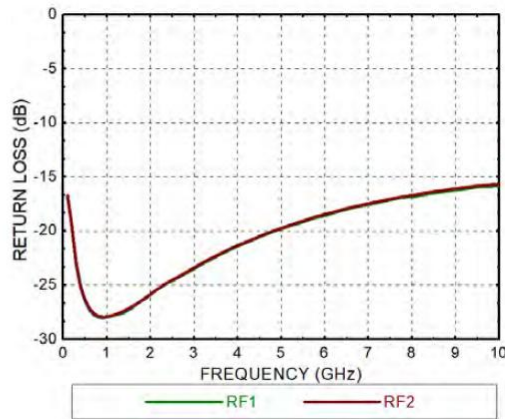
Isolation



Return Loss (ON State)



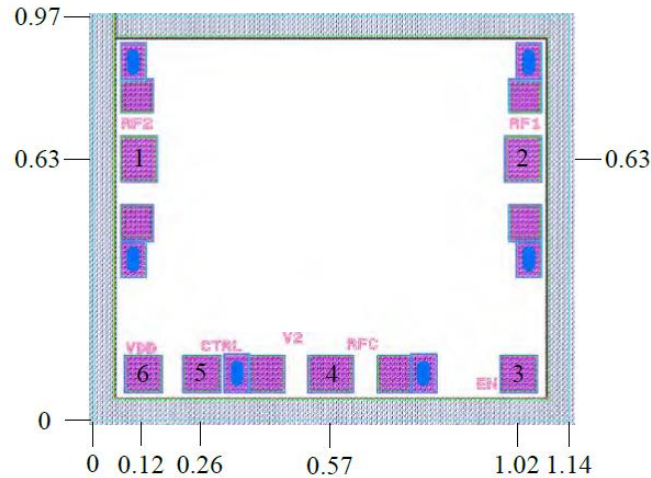
Return Loss (OFF State)





Outline Drawing:

All Dimensions in mm



Pad Description

PAD	Function	Description
1,2	RF2,RF1	RF branch port, blocking capacitor is required externally.
4	RFC	RF common port, blocking capacitor is required externally.
3,5	EN, CTRL	When EN=0V, CTRL=+3.3V, then RF1 is "ON" state, RF2 is "OFF" state; When EN=0V, CTRL=0V, then RF1 is "OFF" state, RF2 is "ON" state; When EN=+3.3V, then RF1 is "OFF" state, RF2 is "OFF" state.
4	VDD	Digital circuit power supply port, connected to +5V voltage.
Die Bottom	GND	Die bottom must be connected to RF/DC ground.

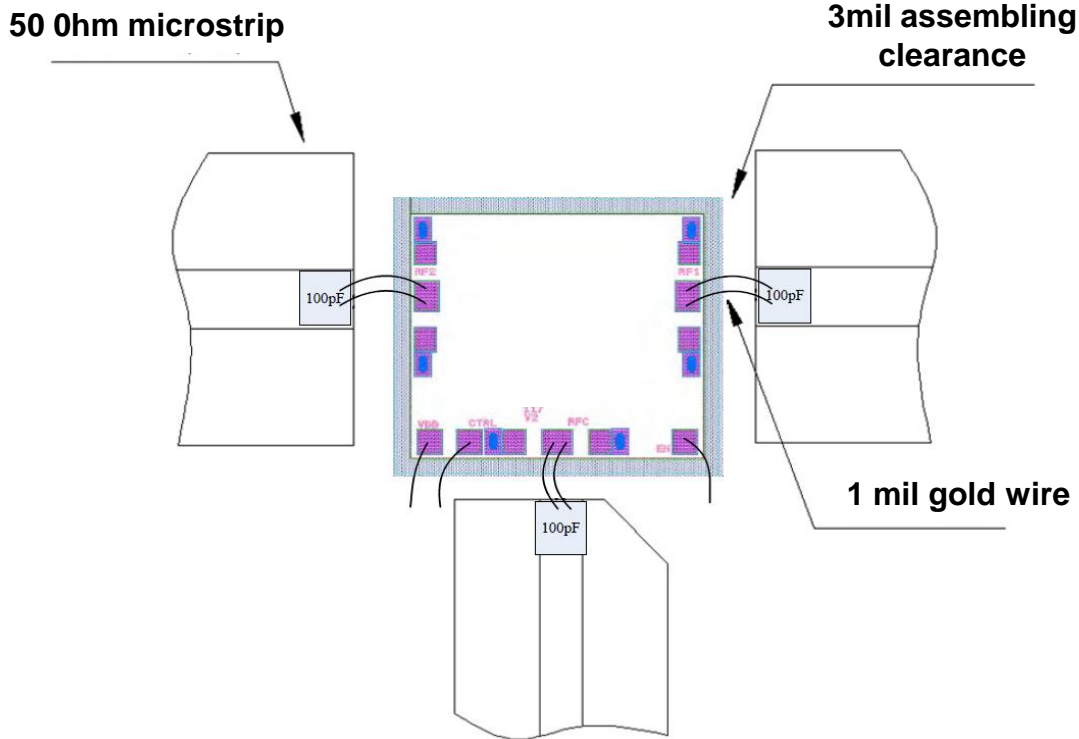
True Table

Function	EN	CTRL
RFC-RF1	0	1
RFC-RF2	0	0
ALL OFF	1	-

"0" voltage range:0~0.8V, "1" voltage range:2.3~5V



Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*80 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Power supply: +6V
2. RF input power: +27dBm
3. Storage temperature: -65°C to +150°C
4. Operating temperature: -55°C to +85°C